

BCM957302A3021AC

Dual-Port 10 Gb/s Ethernet PCI Express Gen3 x8 Network Interface Card

Overview

The Broadcom[®] BCM957302A3021AC is a dual-port 10 Gb/s, PCI-Express Gen3 x8 Network Interface Card that supports both SFP+ optical modules and copper direct attach cable. The card uses the Broadcom BCM57302 10GbE MAC controller with the integrated dual-channel 10GbE SFI transceiver.

Features

- Dual-port pluggable media interface, which may be equipped with 10G SFP+ optical transceiver or with copper direct attach cable.
- Fully compliant to SFF-8402 standard.
- x8 PCI Express v3.0 compliant.
- SR-IOV with up to 128 VFs.
- Function Level Reset (FLR) support.
- TruFlow[™] flow processing engine.
- Virtual Network Termination-VXLAN, NVGRE, GRE encap/decap.
- vSwitch acceleration.
- Tunnel-aware stateless offloads.

Features

- SMBus 2.0.
- MCTP over SMBus.
- PCIe-based UART and KCS.
- Jumbo frames up to 9 KB.
- Advanced Congestion Avoidance.
- Multiqueue, NetQueue, and VMQ.
- IPv4 and IPv6 offloads.
- TCP, UDP, and IP checksum offloads.
- Large Send Offload (LSO).
- Large Receive Offload (LRO).
- TCP Segmentation Offload (TSO).
- Receive-side Scaling (RSS).
- Transmit-side Scaling (TSS).
- VLAN insertion/removal.
- Interrupt coalescing.
- Network boot-PXE, UEFI.
- iSCSI boot.
- MSI and MSI-X.
- Conforms to the PCI Express Card Electromechanical Specification Rev. 3.0.

Applications

Dual-Port 10-Gigabit Ethernet Network Interface Card for Data Centers or Cloud Computing.

Figure 1: BCM957302A3021AC Network Interface Card

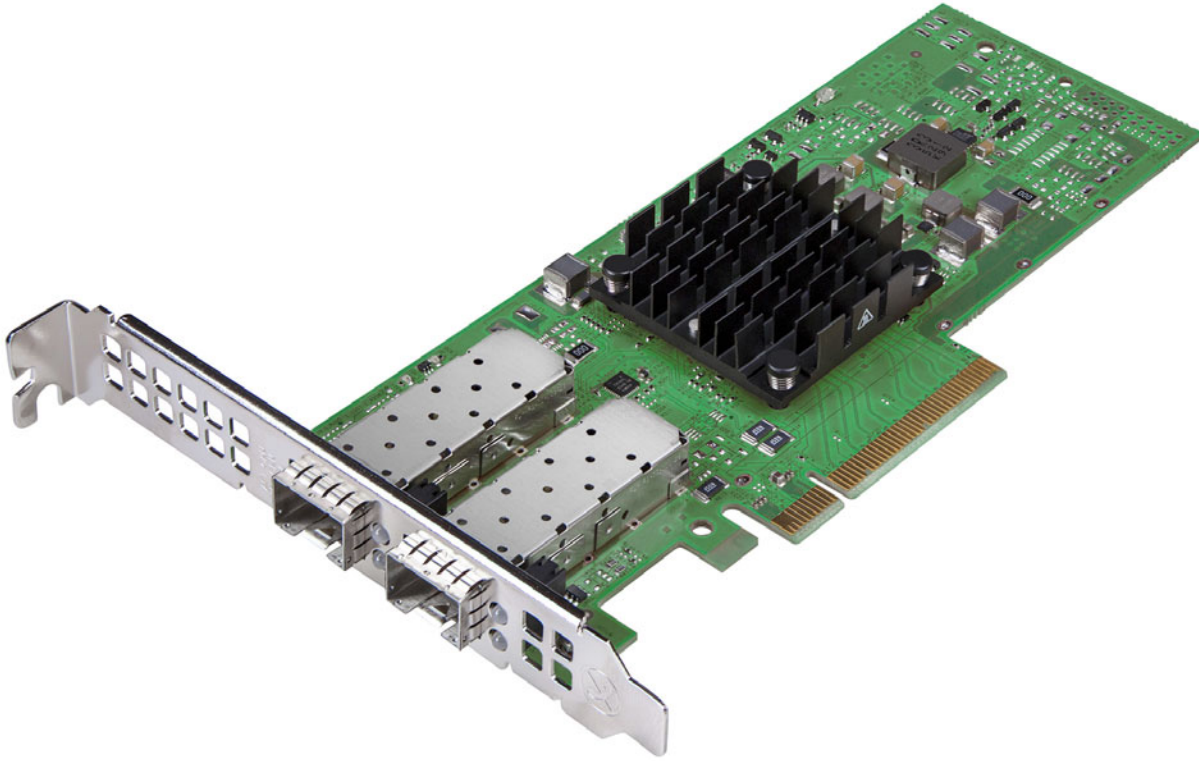


Table of Contents

1 Introduction	4
2 Functional Description	4
2.1 Block Diagram.....	4
2.2 Host Interface Connector	5
2.3 BCM57302	5
2.3.1 Internal Clocks	5
2.3.2 SMBus Interface	5
2.4 Nonvolatile RAM	5
2.5 Heat Sink	5
2.6 DC/DC Regulators	5
2.7 Power Supplies	6
2.8 LED Functions and Locations	6
3 Regulatory and Safety Approvals	7
3.1 Regulatory.....	7
3.2 Safety	7
3.3 Electromagnetic Compatibility (EMC)	7
3.4 Electrostatic Discharge (ESD) Compliance	8
3.5 FCC Statement	8
4 Physical and Electrical Specifications	9
4.1 Board Physical Dimensions	9
4.2 Bracket Outlines and Dimensions	10
4.2.1 Standard-Profile Bracket Outline and Dimensions	10
4.3 Environment Specifications.....	11
5 Ordering Information	11
Revision History	12

1 Introduction

This document is for designers interested in integrating BCM957302A3021AC Network Interface Card into their hardware designs, and for others requiring specific data about the physical characteristics and operation of the BCM957302A3021AC.

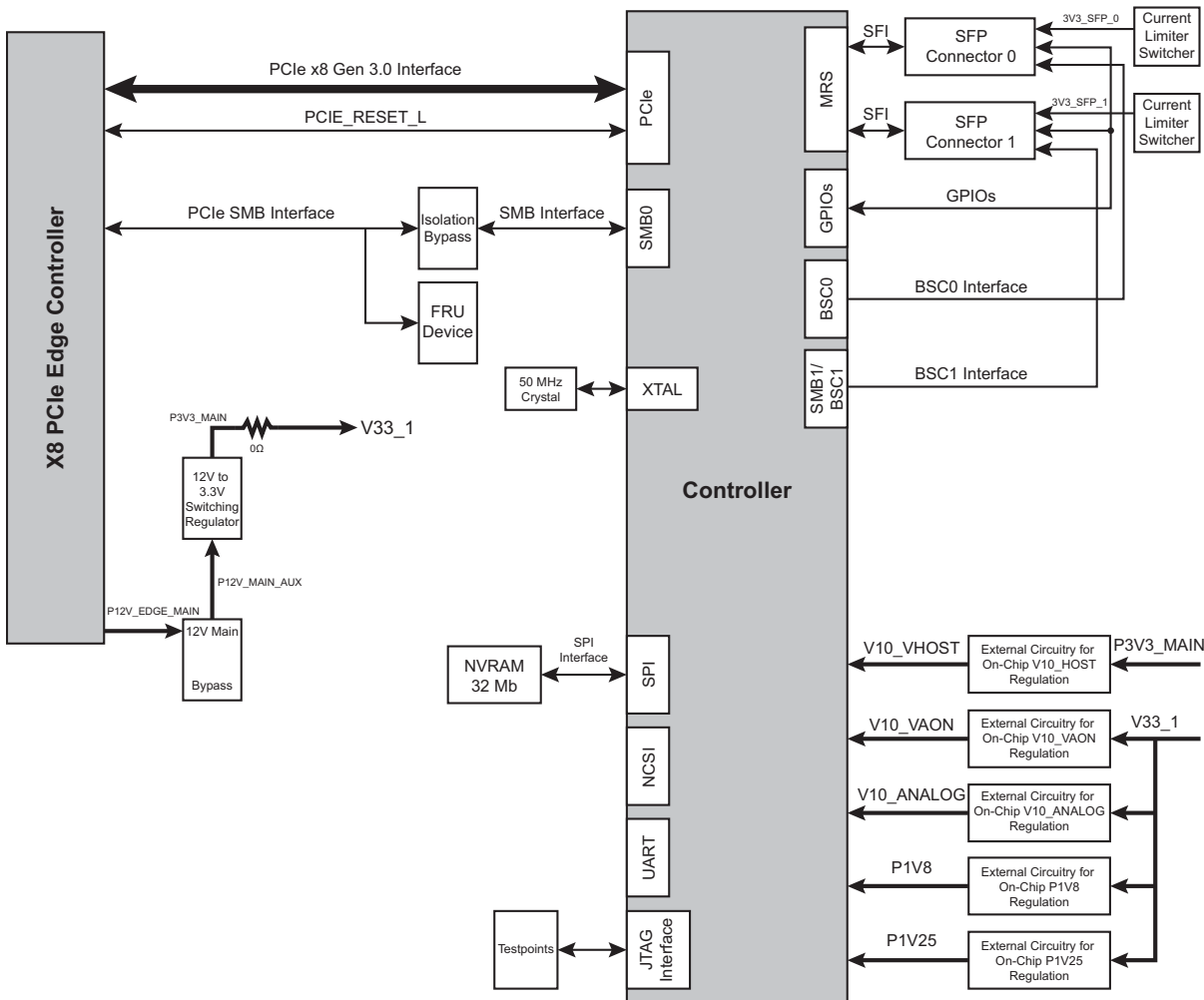
2 Functional Description

This section provides the functional description of the BCM957302A3021AC Network Interface Card.

2.1 Block Diagram

Figure 2 shows the main functional blocks on the BCM957302A3021AC Network Interface Card.

Figure 2: BCM957302A3021AC Block Diagram



2.2 Host Interface Connector

The BCM957302A3021AC NIC is a PCI Express Gen3 x8 add-in card with standard height bracket. The card edge connector complies with the PCI Express Gen3 x8 standard pinout for add-in cards outlined in the PCI Express Electromechanical Specification v3.0 section 6.1, table 6-1.

The PCI Express interface is Gen3 compliant.

NOTE: Refer to section 6 of the PCI Express Electromechanical Specification v3.0 for more details on the card edge connector pinout, and to section 9 for add-in card mechanical information.

2.3 BCM57302

The BCM57302 Ethernet Controller is configured as dual-port 10 Gb/s MAC with an integrated SFI interface on the network side and x8 PCI Express v3.0 interface to the system host.

2.3.1 Internal Clocks

The BCM57302 has an integrated differential oscillator circuit that operates from an external 50 MHz crystal.

2.3.2 SMBus Interface

The BCM57302 Ethernet Controller SMB0 interface supports serial communications between BCM57302 and the system. The interface allows the Ethernet Controller to act as an SMBus master or a slave device.

2.4 Nonvolatile RAM

The BCM57302 Ethernet Controller requires a nonvolatile serial flash memory (NVRAM) to store the device firmware, PCI Configuration space settings (for example, Device ID, Vendor ID), MAC address, and so on. After power-up, the firmware is downloaded into the device memory and executed by the on-chip processor.

2.5 Heat Sink

The passive heat sink is attached to the Ethernet Controller using four spring-loaded push pins that insert into four mounting holes.

To prevent damage to the BCM57302 Ethernet Controller in the event of a missing heat sink, the Network Interface Card is not allowed to power up.

2.6 DC/DC Regulators

The onboard voltage regulators use the 12V edge main power from the host interface connector to derive the necessary power rails for different circuits and components on the board.

2.7 Power Supplies

All power is derived from the PCI Express Host Interface Connector 12V supply pins. These voltage supply pins feed on-board regulators that provide the necessary power to the various components on the card. The NIC has six switching regulators, which power the card's various +1.0V, +1.25V, +1.8V, and +3.3V loads. The 3.3V power (+3.3V) and 3.3V auxiliary power (3.3Vaux) from the PCIe edge connector are also used to supply the power control logics and signals.

2.8 LED Functions and Locations

The SFP+ port supports two LEDs to indicate traffic activities and link speed. The LEDs are visible through the cutout on the bracket as shown in Figure 3. The LED functionality is described in Table 1.

Figure 3: Activity and Link LED Locations

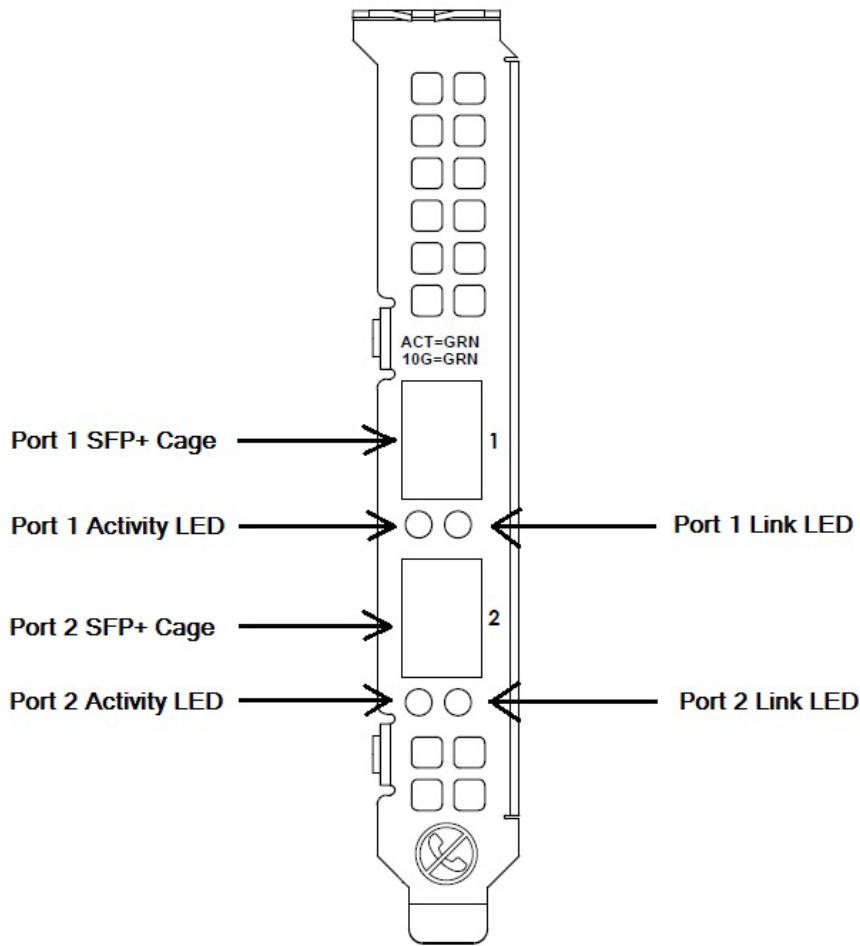


Table 1: LED Functions

NVRAM Manufacturer	Device	Mbit
Activity	Off	No Activity
	Green blinking	Traffic Flowing Activity

Table 1: LED Functions (Continued)

NVRAM Manufacturer	Device	Mbit
Link	Off	No Link
	Green	Linked at 10 Gb/s
	Yellow	Linked at 1 Gb/s

3 Regulatory and Safety Approvals

The following sections detail the Regulatory, Safety, Electromagnetic Compatibility (EMC), and Electrostatic Discharge (ESD) standard compliance for the BCM957302A3021AC Network Interface Card.

3.1 Regulatory

Table 2: Regulatory Approvals

Item	Applicable Standard	Approval (A)/Certificate (C)
CE/European Union	EN 62368-1:2014	CB report and certificate
UL/USA	IEC 62368-1 (ed. 2)	CB report and certificate

3.2 Safety

Table 3: Safety Approvals

Country	Certification Type/Standard	Compliance
International	CB Scheme ICES 003 – Digital Device UL 1977 (connector safety) UL 796 (PCB wiring safety) UL 94 (flammability of parts)	Yes

3.3 Electromagnetic Compatibility (EMC)

Table 4: Electromagnetic Compatibility

Standard/Country	Certification Type	Compliance
CE/EU	EN 55032:2012/AC:2013 Class B EN 55024:2010 EN 61000-3-2:2014 EN 61000-3-3:2013	CE report and CE DoC
FCC/USA	CFR47 Part 15 Subpart B Class B	FCC/IC DoC and EMC report referencing FCC and IC standards
IC/Canada	ICES-003 Class B	FCC/IC DoC and report referencing FCC and IC standards
ACA/Australia, New Zealand	AS/NZS CISPR 22:2009 +A1 :2010	ACA certificate
BSM/Taiwan	CNS 13438 (2006) Class B	BSMI certificate
BSMI/Taiwan	CNS 15663	BSMI certificate/RoHS table

Table 4: Electromagnetic Compatibility (Continued)

Standard/Country	Certification Type	Compliance
MSIP/S. Korea	RRL KN22 Class B KN24	Korea certificate MSIP mark
VCCI/Japan	VCCI V-3 (2015-04)	Copy of VCCI online certificate

3.4 Electrostatic Discharge (ESD) Compliance

Table 5: ESD Compliance Summary

Standard	Certification Type	Compliance
EN 55024:2010 (EN 61000-4-2)	Air/Direct discharge	Yes

3.5 FCC Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Consult the dealer or an experienced radio/TV technician for help.

NOTE: Changes or modifications not expressly approved by the manufacture responsible for compliance could void the user's authority to operate the equipment.

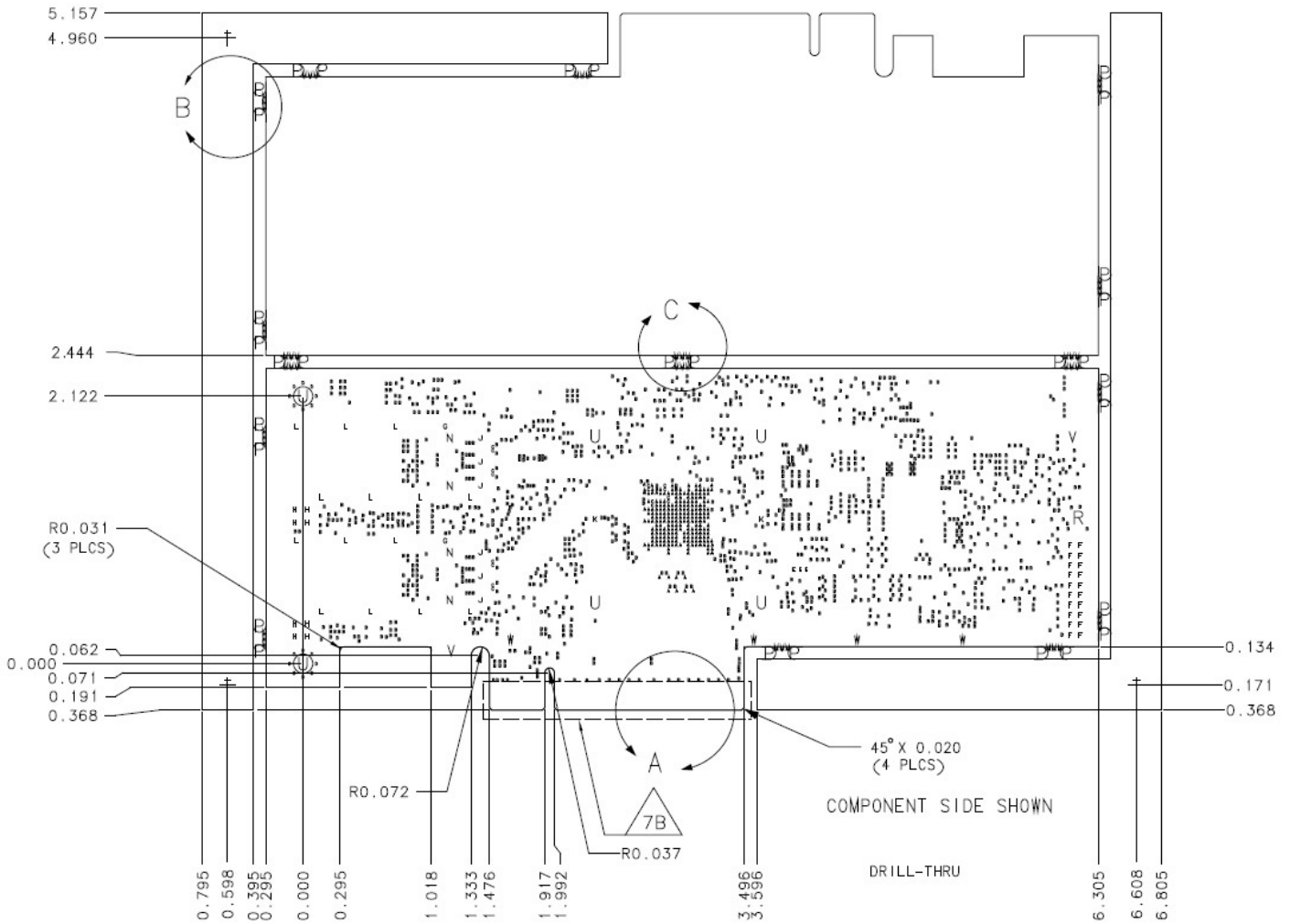
4 Physical and Electrical Specifications

This section outlines the mechanicals of the BCM957302A3021AC Network Interface Card as well as the Environmental Specifications.

4.1 Board Physical Dimensions

The BCM957302A3021AC board dimensions are shown in Figure 4. The dimensions are in inches with a tolerance of ± 0.005 inches.

Figure 4: Board Physical Dimensions



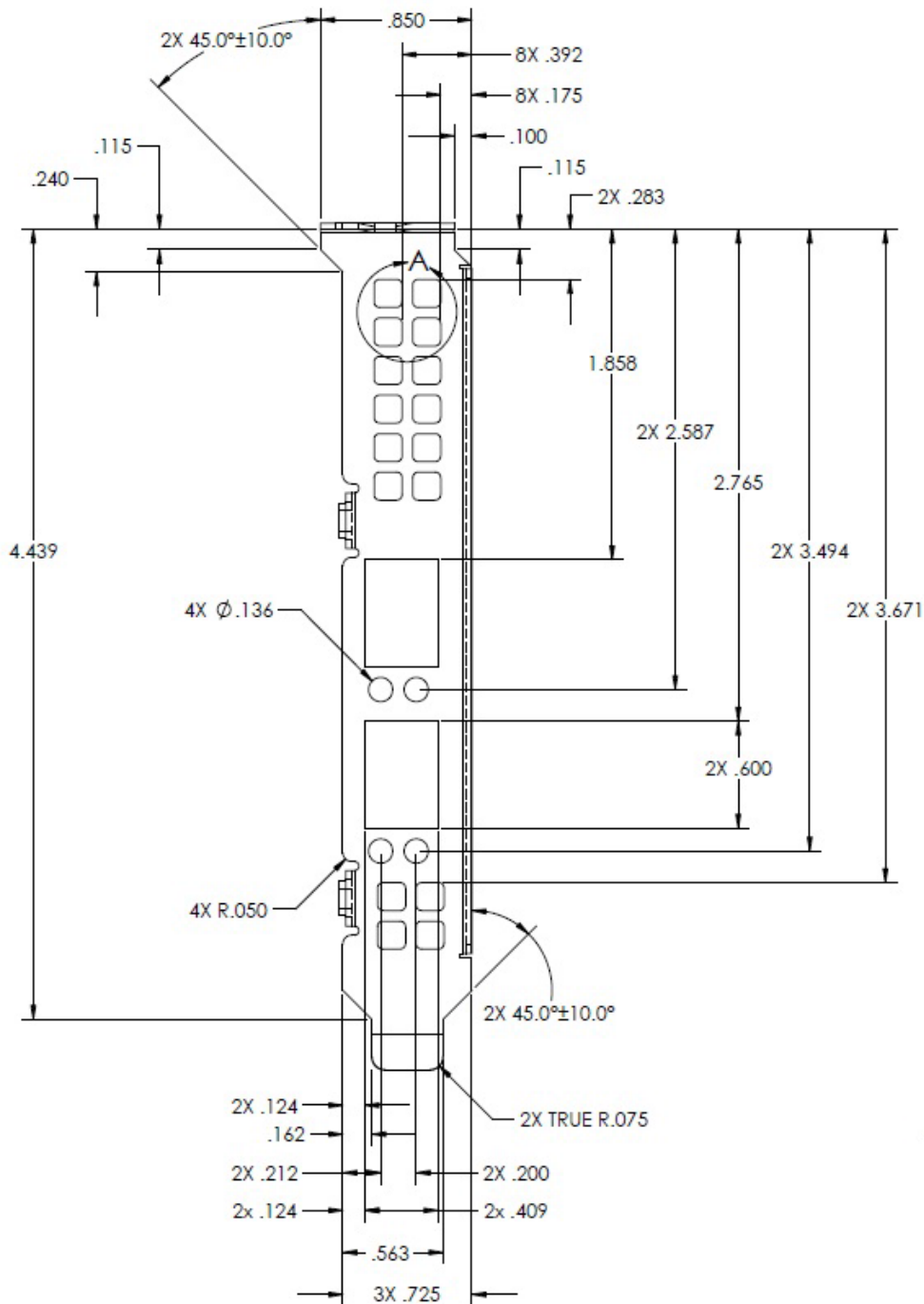
4.2 Bracket Outlines and Dimensions

The BCM957302A3021AC supports a standard bracket.

4.2.1 Standard-Profile Bracket Outline and Dimensions

The standard-profile bracket outline and physical dimensions are shown in [Figure 5](#).

Figure 5: Standard-Profile Bracket Outline and Dimensions



4.3 Environment Specifications

Table 6: Environment Specifications

Parameter	Condition
Storage Temperature	-40°C to +65°C
Storage Humidity	5% to 95% non-condensing
Vibration and Shock	IEC78-2-(*) and IEC721-3-(*)

5 Ordering Information

Table 7: Ordering Information

Part Number	Description
BCM957302A3021AC	Dual-Port 10 Gb/s SFP+ Ethernet PCI Express Network Interface Card; RoHS-compliant

Revision History

957302A3021AC-DS100; December 26, 2017

Initial release.

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